

Non-Silicone Two-Part Thermal Conductive Sealing Glue

LiPOLY EP770 is a silicone-free two-part sealing gap filler. EP770 provides low viscosity and high fluidity. The high deformation material, which can filling the gap closely, cover the tolerance, and has outstanding conductivity, makes is suitable for filling the peculiar gap.

■ FEATURES

- / Thermal conductivity: 2.5 W/m*K
- / Thermally conductive vibration dampening
- / Low mixing viscosity
- / Extremely low Shrinkage rate 0.01%.
- / Epoxy Based material with high hardness for support
- / Slow sedimentation rate due to Resin & powder mixing perfectly via superb processing technology. It leads EP770 material easy to mix and disperse

■ TYPICAL APPLICATION

- / Motor: Torque motor 、 Linear Motor Servo motor
- / 5G smart pole (lighting, Networking, Power supply)
- / IGBT module
- / Electric vehicle motor
- / Electronic components: IC 、 CPU MOS 、 Mother Board
- / Wireless Hub
- / Automotive electronics
- / Between any heat-generating component and a heat sink

■ CONFIGURATIONS

- / Tinplate Can:1 kg
- / Other special and custom sizes are available upon request

■ PRESERVATION

It can be preserved for 24 months under the condition of unopened and under room temperature 25°C.

■ PLEASE NOTE

It is recommended to preheat the material to 40°C for 20 minutes or 50°C for 10 minutes if ambient temperature is less than 25°C for better extrusion and mixing.

■ TYPICAL PROPERTIES

PROPERTY	EP770	TEST METHOD	UNIT
Color	Black	Visual	-
Resin base	Epoxy	-	-
A:B	100:10	-	-
Viscosity A	200	ISO 3219	Pa.s
Viscosity mixed	2	ISO 3219	Pa.s
Shrinkage rate	0.01	ASTM D2566	%
Density	1.8	ASTM D792	g/cm ³
Application temperature	-60~150	-	°C
Curing condition 1	80°C/1.5 hrs	By LiPOLY	-
Curing condition 2	25°C/35 hrs	By LiPOLY	-
Hardness	80	ASTM D2240	Shore A
Shelf life	24 months	-	-
ROHS & REACH	Compliant	-	-
ELECTRICAL			
Dielectric breakdown	14	ASTM D149	KV/mm
Volume resistivity	>10 ¹¹	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	2.5	ASTM D5470	W/m*K

